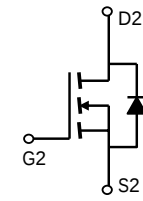
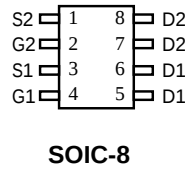


General Description

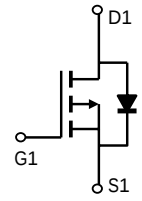
The AO4612 uses advanced trench technology MOSFETs to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used in H-bridge, Inverters and other applications.

Features

n-channel	p-channel
$V_{DS} (V) = 60V$	-60V
$I_D = 5.0A (V_{GS}=10V)$	-3.8A ($V_{GS} = -10V$)
$R_{DS(ON)}$	$R_{DS(ON)}$
$< 33m\Omega (V_{GS}=10V)$	$< 75m\ \Omega (V_{GS} = -10V)$
$< 42m\Omega (V_{GS}=4.5V)$	$< 85m\ \Omega (V_{GS} = -4.5V)$



n-channel



p-channel

100% Rg tested

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted					
Parameter		Symbol	Max n-channel	Max p-channel	Units
Drain-Source Voltage		V_{DS}	60	-60	V
Gate-Source Voltage		V_{GS}	± 20	± 20	V
Continuous Drain Current ^A	$T_A=25^\circ C$	I_D	5.0	-3.8	A
	$T_A=70^\circ C$		3.6	-2.6	
Pulsed Drain Current ^B		I_{DM}	20	-20	
Power Dissipation	$T_A=25^\circ C$	P_D	2	2	W
	$T_A=70^\circ C$		1.28	1.28	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	-55 to 150	$^\circ C$
Thermal Characteristics: n-channel and p-channel					
Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$t \leq 10s$	$R_{\theta JA}$	48	62.5	$^\circ C/W$
	Steady-State		74	90	$^\circ C/W$
Maximum Junction-to-Lead ^C	Steady-State	$R_{\theta JL}$	35	40	$^\circ C/W$

N Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	60			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^{\circ}\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1	1.3	2	V
$I_{D(ON)}$	On state drain current	$V_{GS}=10\text{V}$, $V_{DS}=5\text{V}$	20			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=5.0\text{A}$ $T_J=125^{\circ}\text{C}$		33 79	56	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=3\text{A}$		42	65	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=4.5\text{A}$		11		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}$, $V_{GS}=0\text{V}$		0.74	1	V
I_S	Maximum Body-Diode Continuous Current				3	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=30\text{V}$, $f=1\text{MHz}$		450	540	pF
C_{oss}	Output Capacitance			60		pF
C_{rss}	Reverse Transfer Capacitance			25		pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$		1.65	2	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}$, $V_{DS}=30\text{V}$, $I_D=4.5\text{A}$		8.5	10.5	nC
$Q_g(4.5\text{V})$	Total Gate Charge			4.3	5.5	nC
Q_{gs}	Gate Source Charge			1.6		nC
Q_{gd}	Gate Drain Charge			2.2		nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=10\text{V}$, $V_{DS}=30\text{V}$, $R_L=6.7\Omega$, $R_{GEN}=3\Omega$		4.7	7	ns
t_r	Turn-On Rise Time			2.3	4.5	ns
$t_{D(off)}$	Turn-Off DelayTime			15.7	24	ns
t_f	Turn-Off Fall Time			1.9	4	ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=4.5\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		27.5	35	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=4.5\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		32		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any a given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D: The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in ² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The SOA curve provides a single pulse rating. Rev3: Oct 2010

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: N-CHANNEL

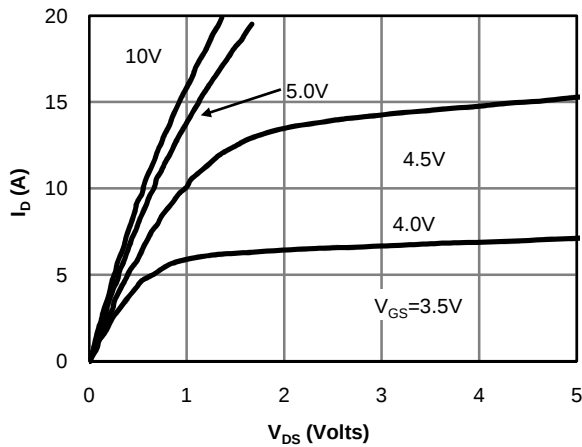


Fig 1: On-Region Characteristics

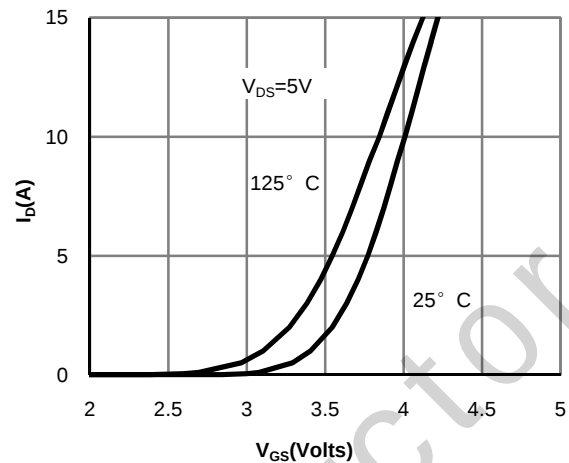


Figure 2: Transfer Characteristics

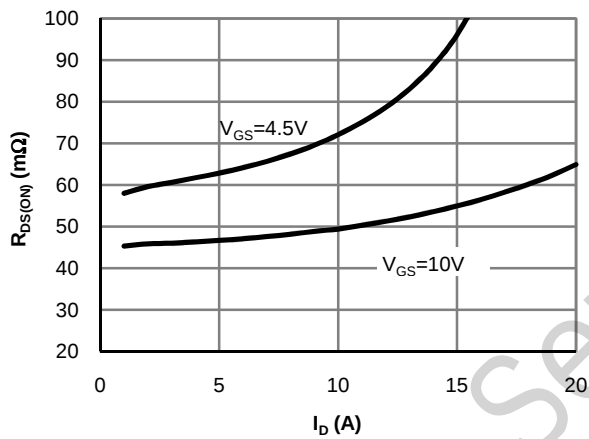


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

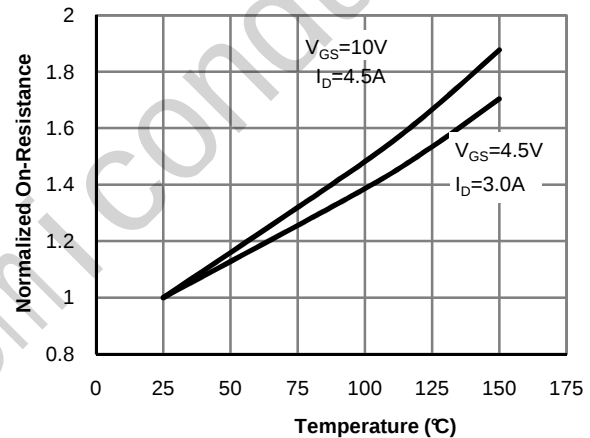


Figure 4: On-Resistance vs. Junction Temperature

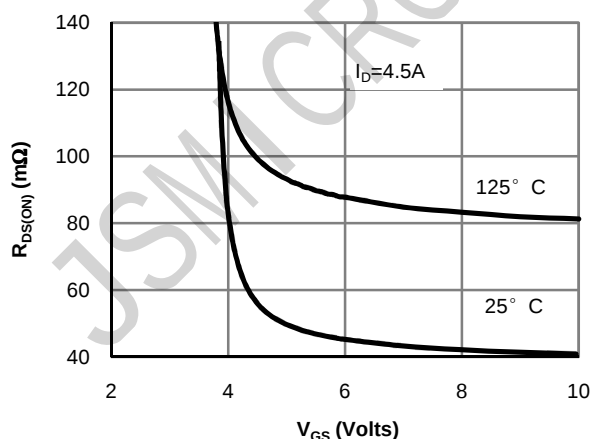


Figure 5: On-Resistance vs. Gate-Source Voltage

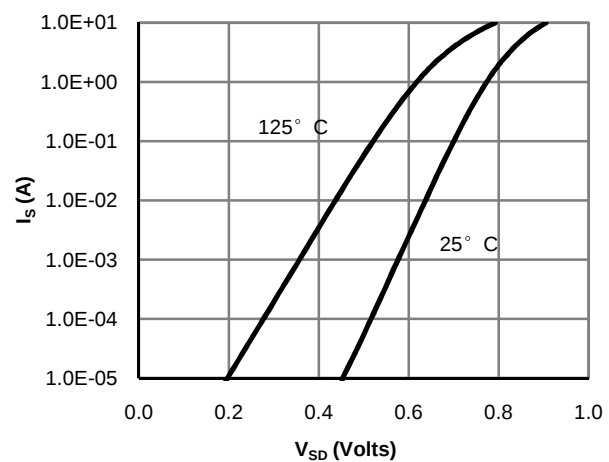


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: N-CHANNEL

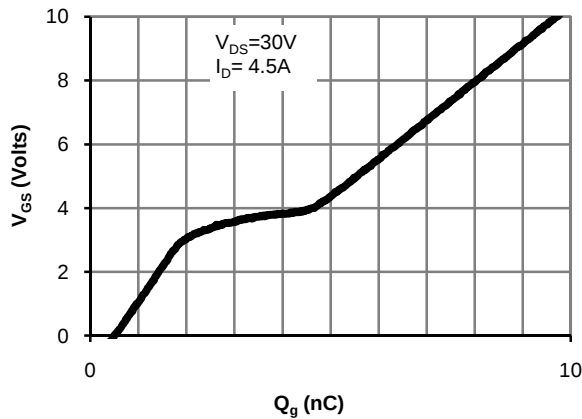


Figure 7: Gate-Charge Characteristics

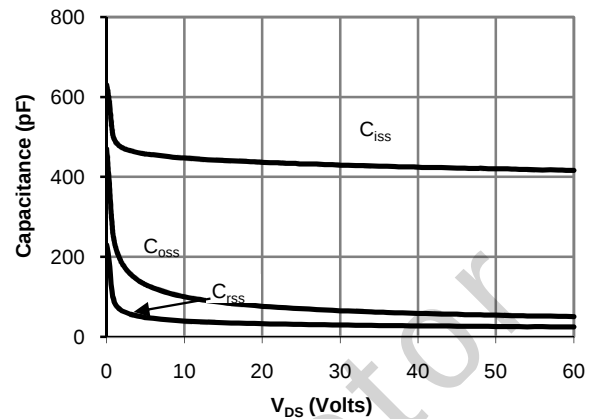


Figure 8: Capacitance Characteristics

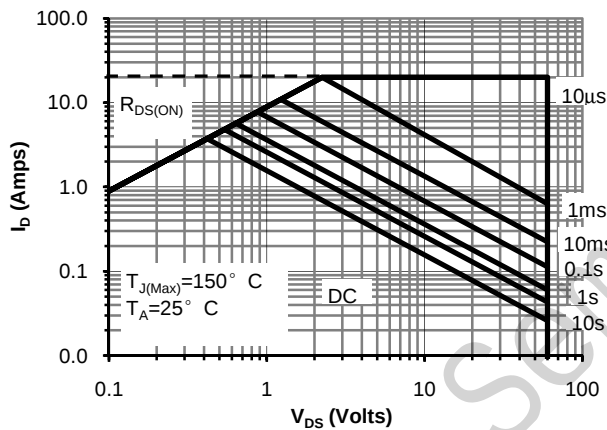


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

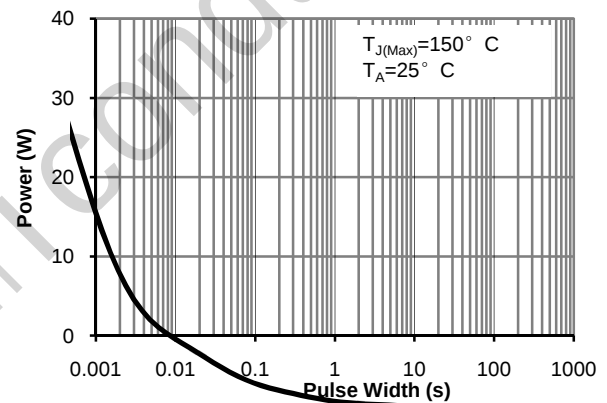


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

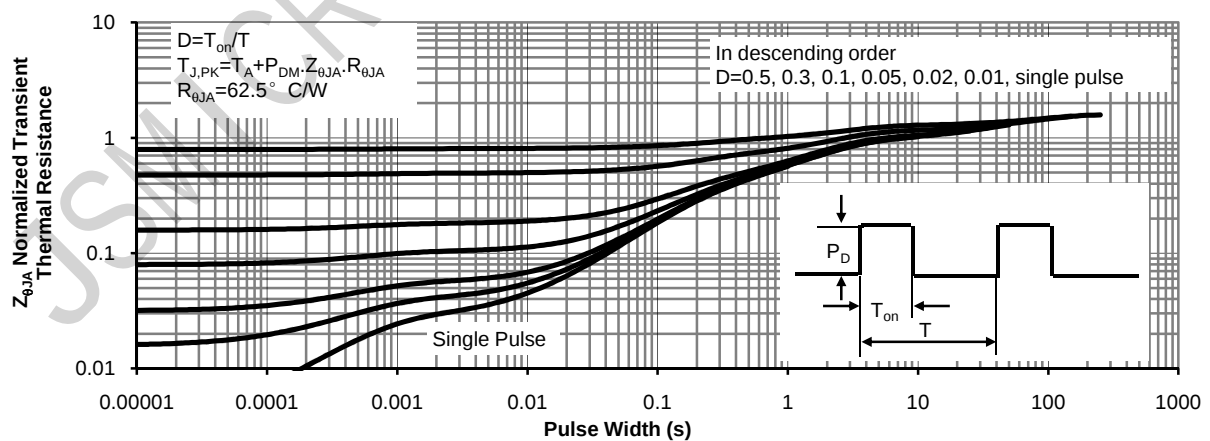


Figure 11: Normalized Maximum Transient Thermal Impedance

P-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-60			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-60\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^{\circ}\text{C}$			-1 -5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-1	-1.65	-3	V
$I_{D(ON)}$	On state drain current	$V_{GS}=-10\text{V}$, $V_{DS}=-5\text{V}$	-20			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-3.2\text{A}$		75	95	m Ω
		$T_J=125^{\circ}\text{C}$		145		
		$V_{GS}=-4.5\text{V}$, $I_D=-2.0\text{A}$		85	105	m Ω
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=-3.2\text{A}$		9		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}$, $V_{GS}=0\text{V}$		-0.73	-1	V
I_S	Maximum Body-Diode Continuous Current				-3	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=-30\text{V}$, $f=1\text{MHz}$		930	1120	pF
C_{oss}	Output Capacitance			85		pF
C_{rss}	Reverse Transfer Capacitance			35		pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$		7.2	9	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge (10V)	$V_{GS}=-10\text{V}$, $V_{DS}=-30\text{V}$, $I_D=-3.2\text{A}$		16	20	nC
$Q_g(4.5\text{V})$	Total Gate Charge (4.5V)			8	10	nC
Q_{gs}	Gate Source Charge			2.5		nC
Q_{gd}	Gate Drain Charge			3.2		nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=-10\text{V}$, $V_{DS}=-30\text{V}$, $R_L=9.4\Omega$, $R_{GEN}=3\Omega$		8	12	ns
t_r	Turn-On Rise Time			3.8	7.5	ns
$t_{D(off)}$	Turn-Off DelayTime			31.5	48	ns
t_f	Turn-Off Fall Time			7.5	15	ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-3.2\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		27	35	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-3.2\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		32		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any a given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

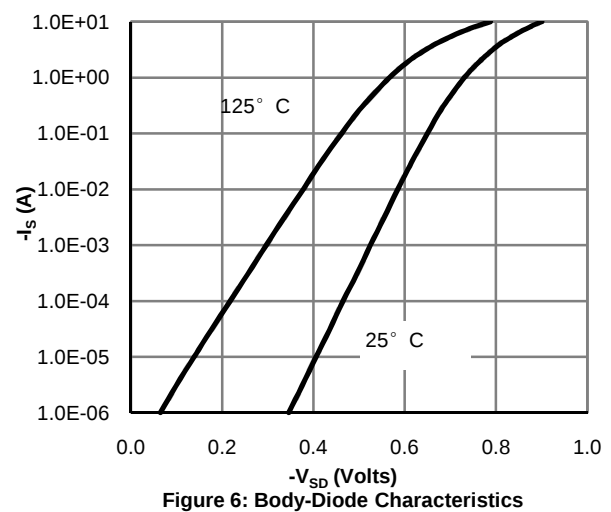
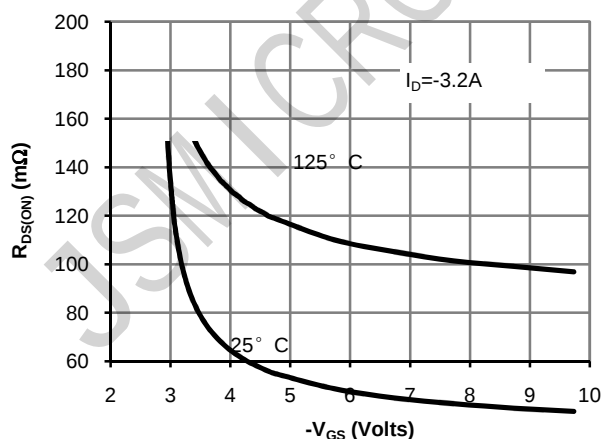
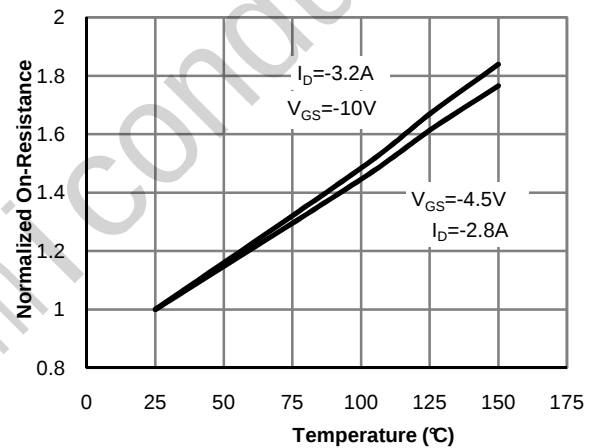
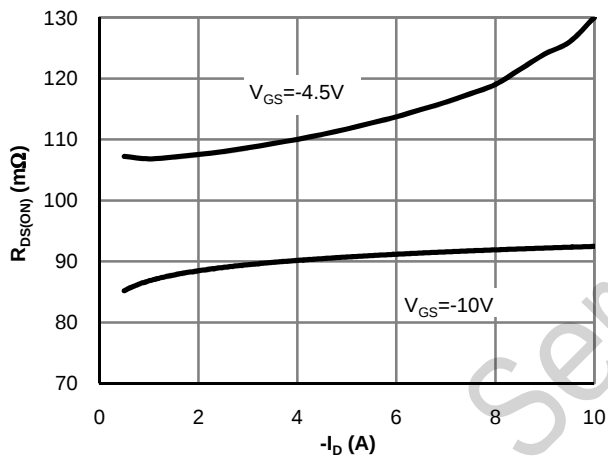
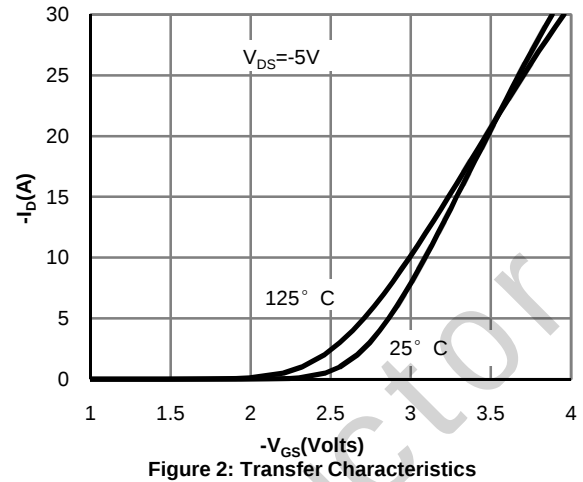
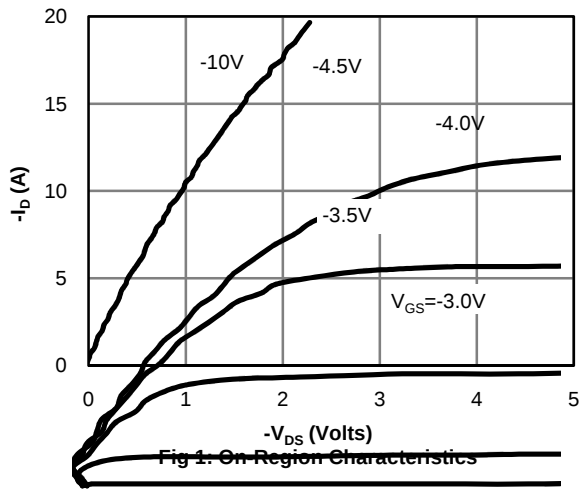
B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D: The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The SOA curve provides a single pulse rating.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: P-CHANNEL



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: P-CHANNEL

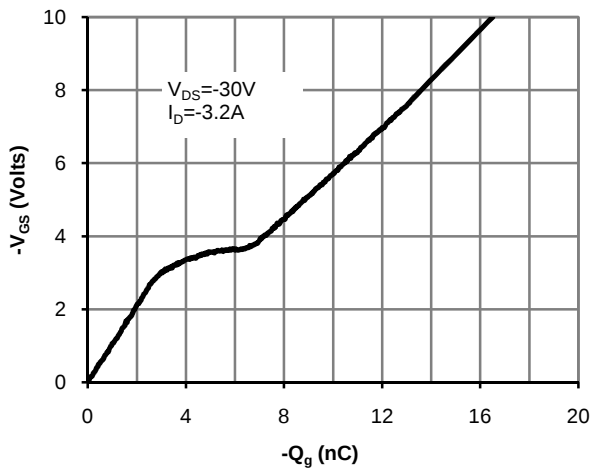


Figure 7: Gate-Charge Characteristics

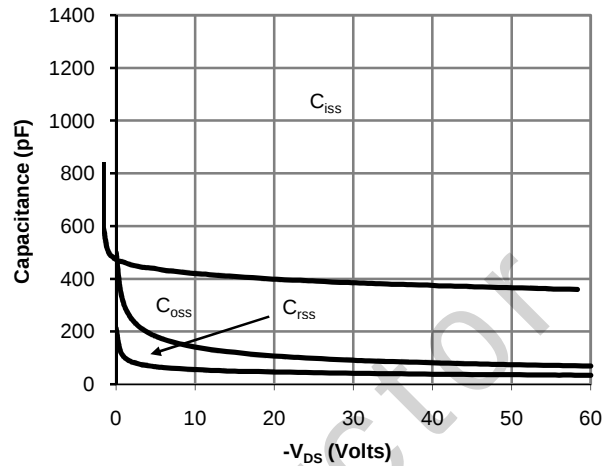


Figure 8: Capacitance Characteristics

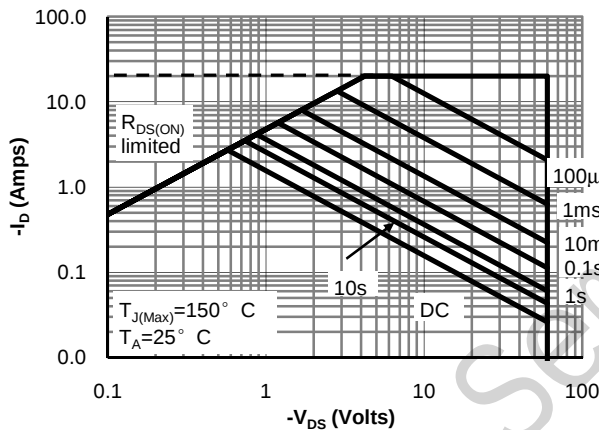


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

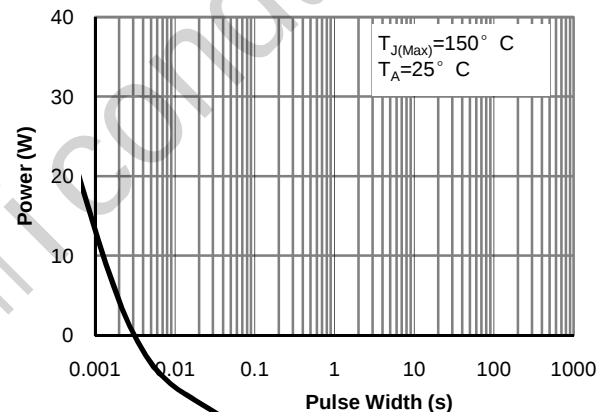


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

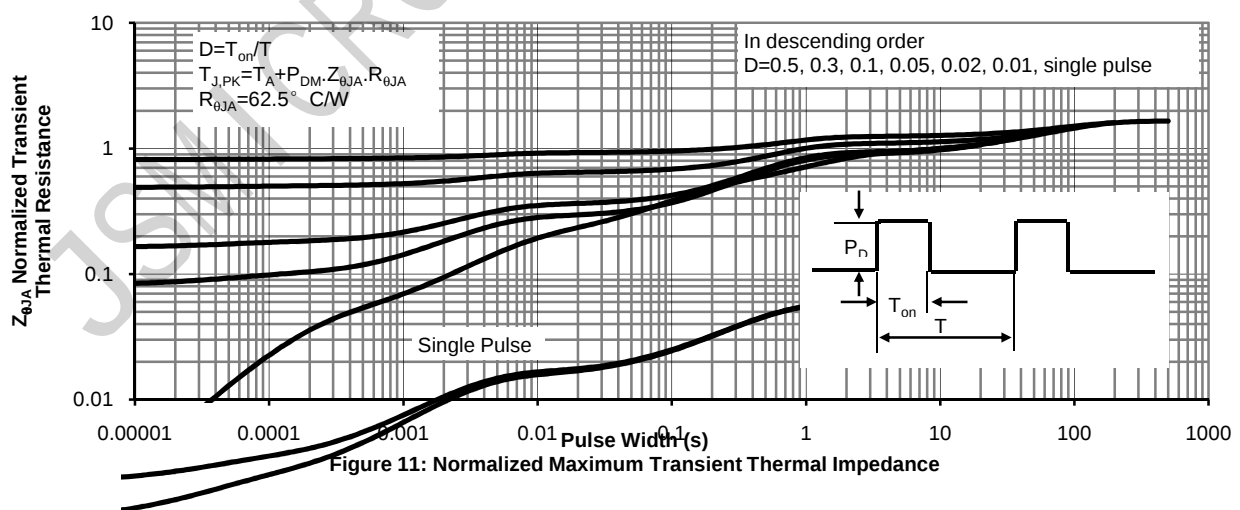


Figure 11: Normalized Maximum Transient Thermal Impedance